

TIDA-00563 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	PCB1	1		TIDA-00563	Any	Printed Circuit Board	
2	C1, C3	2	2.2uF	C0603C225K8PACTU	Kemet	CAP, CERM, 2.2 uF, 10 V, +/- 10%, X5R, 0603	0603
3	C2, C7, C11, C25, C26, C27	6	0.1uF	C1005X7R1H104K050BB	TDK	CAP, CERM, 0.1 uF, 50 V, +/- 10%, X7R, 0402	0402
4	C5, C8	2	10pF	500R07S100JV4T	Johanson Technology	CAP, CERM, 10 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
5	C6	1	4.7uF	GRM21BR71C475KA73L	MuRata	CAP, CERM, 4.7 uF, 16 V, +/- 10%, X7R, 0805	0805
6	C10	1	1uF	GRM155R61A105KE15D	MuRata	CAP, CERM, 1 uF, 10 V, +/- 10%, X5R, 0402	0402
7	C12	1	0.015uF	GRM188R71C153KA01D	MuRata	CAP, CERM, 0.015 uF, 16 V, +/- 10%, X7R, 0603	0603
8	C13, C14	2	18pF	GRM1555C1H180JA01D	MuRata	CAP, CERM, 18 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
9	C15	1	2200pF	GRM155R70J222KA01D	MuRata	CAP, CERM, 2200 pF, 6.3 V, +/- 10%, X7R, 0402	0402
10	C16, C17, C21, C22	4	18pF	GRM1885C2A180JA01D	MuRata	CAP, CERM, 18 pF, 100 V, +/- 5%, C0G/NP0, 0603	0603
11	C18, C20	2	1300pF	0402YC132KAT2A	AVX	CAP, CERM, 1300 pF, 16 V, +/- 10%, X7R, 0402	0402
12	C19	1	0.47uF	C0603C474K8RACTU	Kemet	CAP, CERM, 0.47 uF, 10 V, +/- 10%, X7R, 0603	0603
13	C23	1	10uF	C1608X5R1A106M	TDK	CAP, CERM, 10 uF, 10 V, +/- 20%, X5R, 0603	0603
14	C TANK	1	330pF	C1608C0G1H331F080AA	TDK	CAP, CERM, 330 pF, 50 V, +/- 1%, C0G/NP0, 0603	0603
15	D1	1	5.6V	MMSZ5232B-7-F	Diodes Inc.	Diode, Zener, 5.6 V, 500 mW, SOD-123	SOD-123
16	D2	1	Green	150060GS75000	Würth Elektronik	LED, Green, SMD	LED_0603
17	D3	1	Red	150060RS75000	Würth Elektronik	LED, Red, SMD	LED_0603
18	D4	1	20V	SBR0220T5-7-F	Diodes Inc.	Diode, Schottky, 20 V, 0.2 A, SOD-523	SOD-523
19	J1, J7, J9	3		PEC03SAAN	Sullins Connector Solutions	Header, 100mil, 3x1, Tin plated, TH	Header, 3 PIN, 100mil, Tin
20	J2, J4	2		SSW-110-23-F-D	Samtec	Connector, Receptacle, 100mil, 10x2, Gold plated, TH	10x2 Receptacle
21	J3	1		ZX62R-B-5P	Hirose Electric Co. Ltd.	Connector, Receptacle, Micro-USB Type B, SMT	Connector USB Mini B
22	J5	1		SBH11-PBPC-D07-ST-BK	Sullins Connector Solutions	Header (shrouded), 100 mil, 7x2, Gold plated, TH	7x2 Shrouded Header
23	J6	1		PPTC021LGBN-RC	Sullins Connector Solutions	Receptacle, 2.54 mm, 2x1, Tin, R/A, SMT	Receptacle, 2.54 mm, 2x1, R/A, SMT
24	J8, J10	2		TSW-102-07-T-S	Samtec	Header, 2.54 mm, 2x1, Tin, TH	Header, 2.54 mm, 2x1, TH
25	L1	1	10uH	VLS201610ET-100M	TDK	Inductor, Shielded, Ferrite, 10 uH, 0.4 A, 1.38 ohm, SMD	2.0x0.95x1.6mm
26	R1	1	1.40k	ERJ-2RKF1401X	Panasonic	RES, 1.40 k, 1%, 0.1 W, 0402	0402
27	R2, R4	2	27	CRCW040227R0JNED	Vishay-Dale	RES, 27, 5%, 0.063 W, 0402	0402
28	R3, R9	2	33k	CRCW040233K0JNED	Vishay-Dale	RES, 33 k, 5%, 0.063 W, 0402	0402
29	R5	1	33	CRCW060333R0JNEA	Vishay-Dale	RES, 33, 5%, 0.1 W, 0603	0603
30	R7, R8	2	1.0k	CRCW04021K00JNED	Vishay-Dale	RES, 1.0 k, 5%, 0.063 W, 0402	0402
31	R10, R11	2	0	ERJ-3GEY0R00V	Panasonic	RES, 0, 5%, 0.1 W, 0603	0603
32	R12, R13	2	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	0402
33	R14	1	4.99	RC0603FR-074R99L	Yageo America	RES, 4.99, 1%, 0.1 W, 0603	0603
34	R15	1	100	ERJ-2RKF1000X	Panasonic	RES, 100, 1%, 0.1 W, 0402	0402
35	S2	1		SKRKAEE010	Alps	Switch, Push Button, SMD	2.9x2x3.9mm SMD
36	SH-J1, SH-J7, SH-J8, SH-J9, SH-J10	5	1x2	969102-0000-DA	3M	Shunt, 100mil, Gold plated, Black	Shunt
37	TP3	1	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
38	TP4, TP8	2	White	5002	Keystone	Test Point, Miniature, White, TH	White Miniature Testpoint
39	TP9, TP10	2	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
40	U1	1		LP5951MG-3.3/NOBP	Texas Instruments	Micropower, 150mA Low-Dropout CMOS Voltage Regulator, 5-pin SC-70, Pb-Free	MAA05A
41	U2	1		TPD2E001DRLR	Texas Instruments	Low-Capacitance +/- 15 kV ESD-Protection Array for High-Speed Data Interfaces, 2 Channels, -40 to +85 degC, 5-pin SOT (DRL), Green (RoHS & no Sb/Br)	DRL0005A
42	U3, U6	2		TPD1E10B06DPYR	Texas Instruments	ESD in 0402 Package with 10 pF Capacitance and 6 V Breakdown, 1 Channel, -40 to +125 degC, 2-pin X2SON (DPY), Green (RoHS & no Sb/Br)	DPY0002A
43	U4	1		MSP430F5528IRGC	Texas Instruments	Mixed Signal MicroController, RGC0064B	RGC0064B
44	U5	1		LDC1101DRC	Texas Instruments	1.8V High Resolution Inductance to Digital Converter, DRC0010J	DRC0010J
45	Y1	1		ABM8-24.000MHZ-B2-T	Abracon Corporation	Crystal, 24.000MHz, 18pF, SMD	3.2x0.8x2.5mm
46	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	N/A

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